

General Features

- Advanced Trench Technology
- Lead free product is acquired
- Provide Excellent RDS(ON) and Low Gate Charge

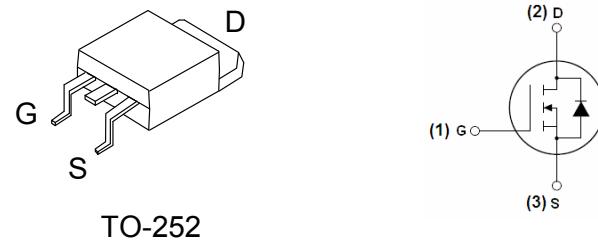
Product Summary



V_{DSS}	100	V
$R_{DS(ON)-Typ}$	24	$m\Omega$
I_D	34	A

Application

- Load Switch
- PWM Application
- Power management



Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	34	A
		$T_c = 100^\circ C$	20	A
I_{DM}	Pulsed Drain Current ^{note1}		120	A
EAS	Single Pulsed Avalanche Energy ^{note2}		110	mJ
P_D	Power Dissipation	$T_c = 25^\circ C$	63	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		2.5	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	$^\circ C$



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ASDM100N34KQ

100V N-Channel MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=20\text{A}$	-	24	32	mΩ
		$V_{GS}=4.5\text{V}$, $I_D=10\text{A}$	-	26	36	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	1500	-	pF
C_{oss}	Output Capacitance		-	380	-	pF
C_{rss}	Reverse Transfer Capacitance		-	252	-	pF
Q_g	Total Gate Charge	$V_{DS}=30\text{V}$, $I_D=15\text{A}$, $V_{GS}=10\text{V}$	-	23	-	nC
Q_{gs}	Gate-Source Charge		-	5	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	4	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30\text{V}$, $I_D=15\text{A}$, $R_G=1.8\Omega$, $V_{GS}=10\text{V}$	-	12.6	-	ns
t_r	Turn-on Rise Time		-	6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	22	-	ns
t_f	Turn-off Fall Time		-	5.3	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	30	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	120	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_S=30\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$IF=15\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	71	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	145	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $V_G=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$



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Test Circuit

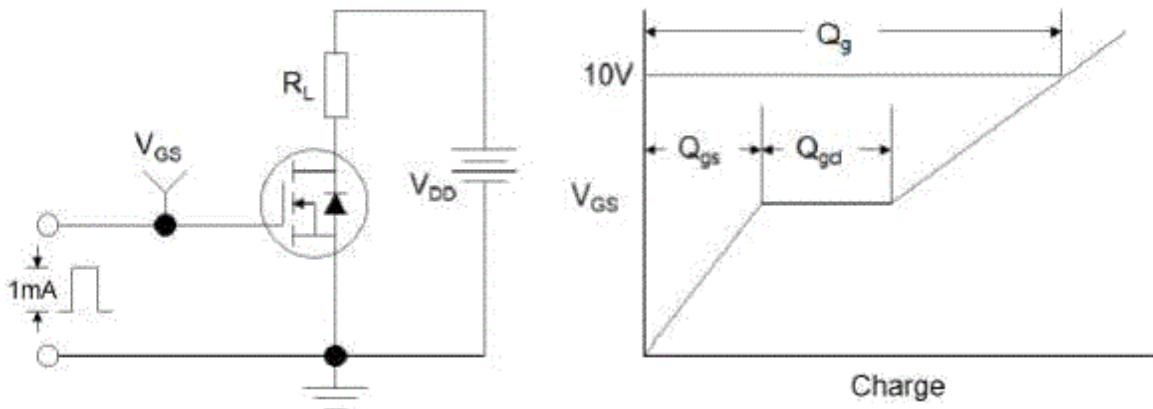


Figure 1: Gate Charge Test Circuit & Waveform

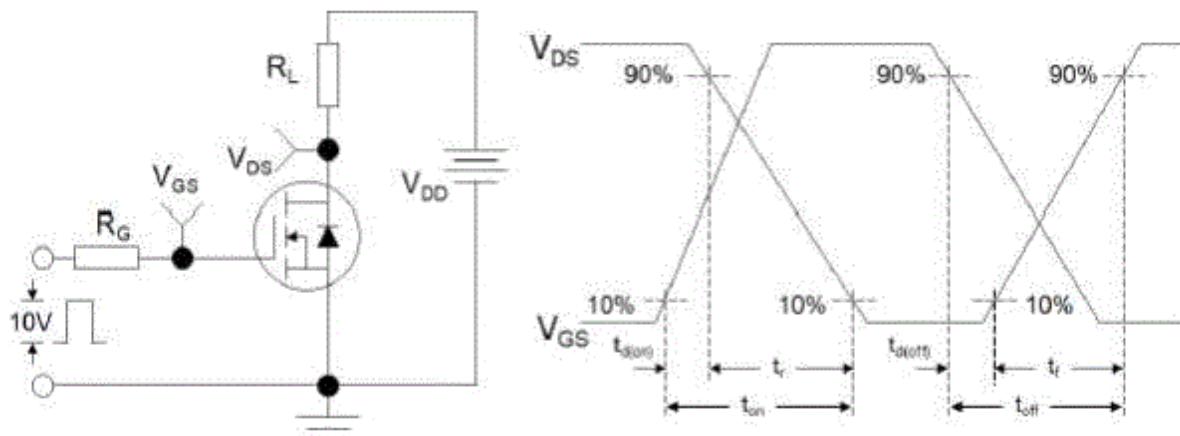


Figure 2: Resistive Switching Test Circuit & Waveforms

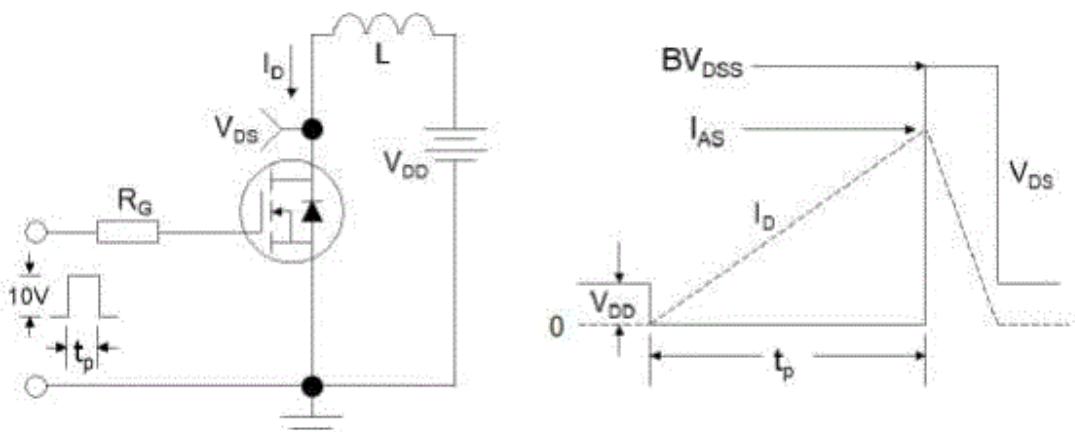


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

Typical Electrical and Thermal Characteristics (Curves)

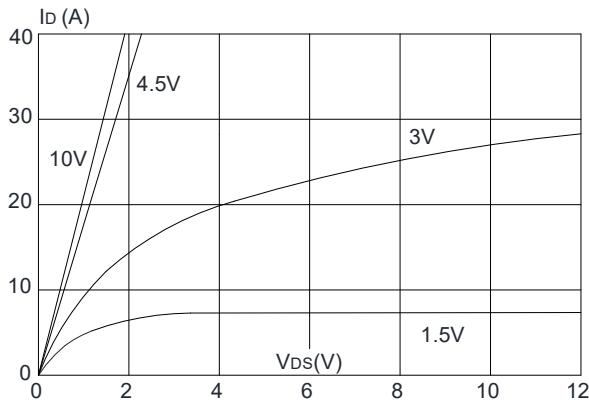


Figure 1: Output Characteristics

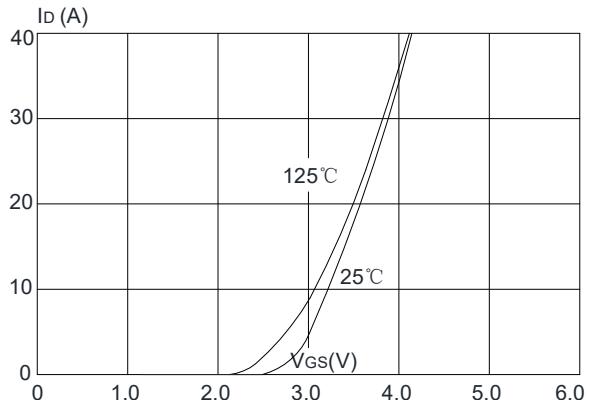


Figure 2: Typical Transfer Characteristics

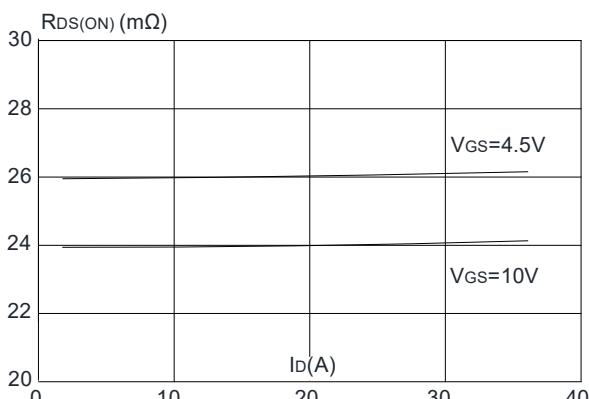


Figure 3: On-resistance vs. Drain Current

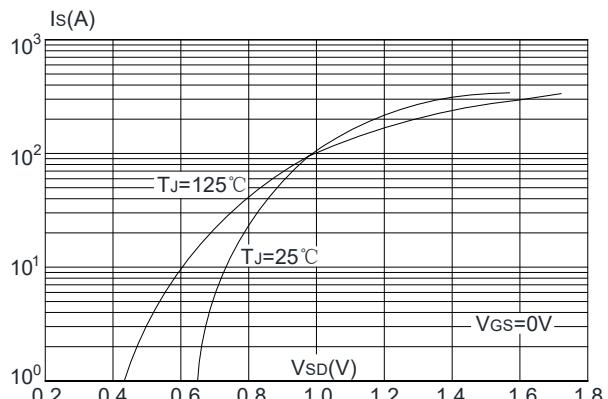


Figure 4: Body Diode Characteristics

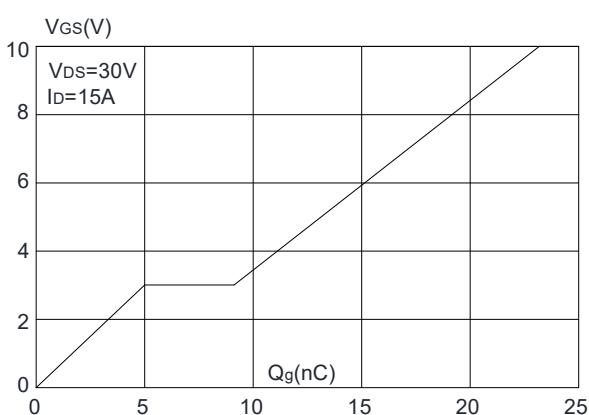


Figure 5: Gate Charge Characteristics

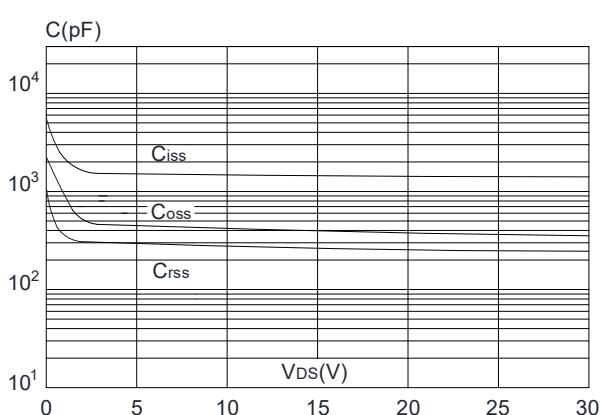


Figure 6: Capacitance Characteristics



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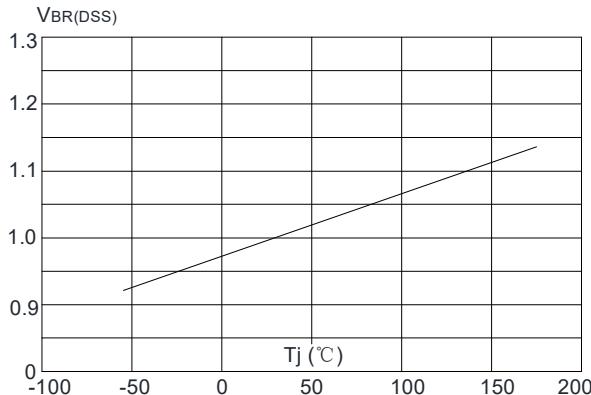


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

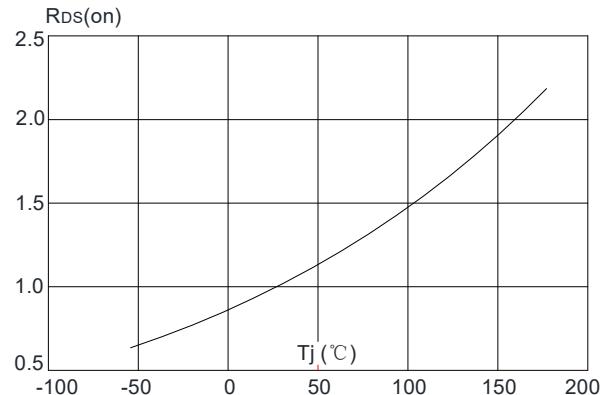


Figure 8: Normalized on Resistance vs. Junction Temperature

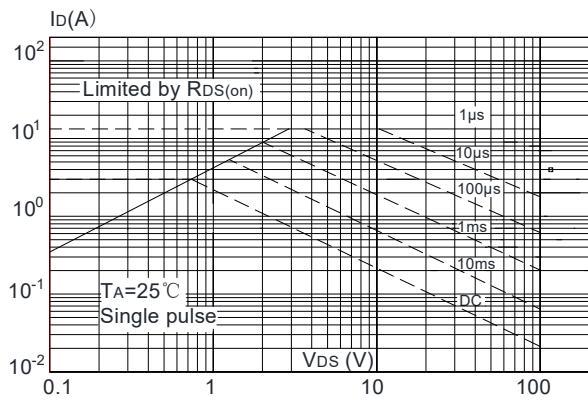


Figure 9: Maximum Safe Operating Area

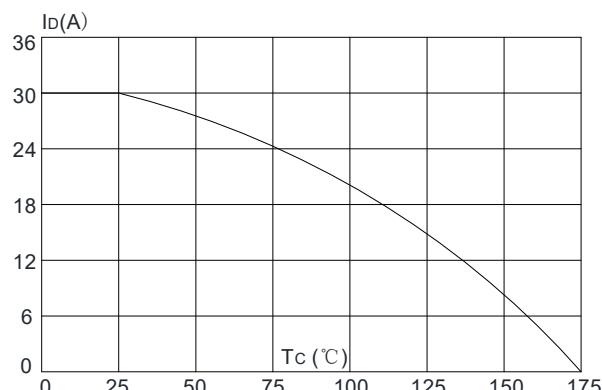


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

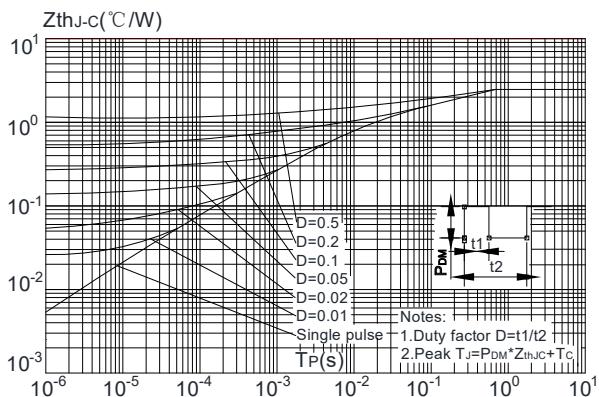
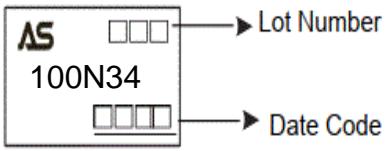


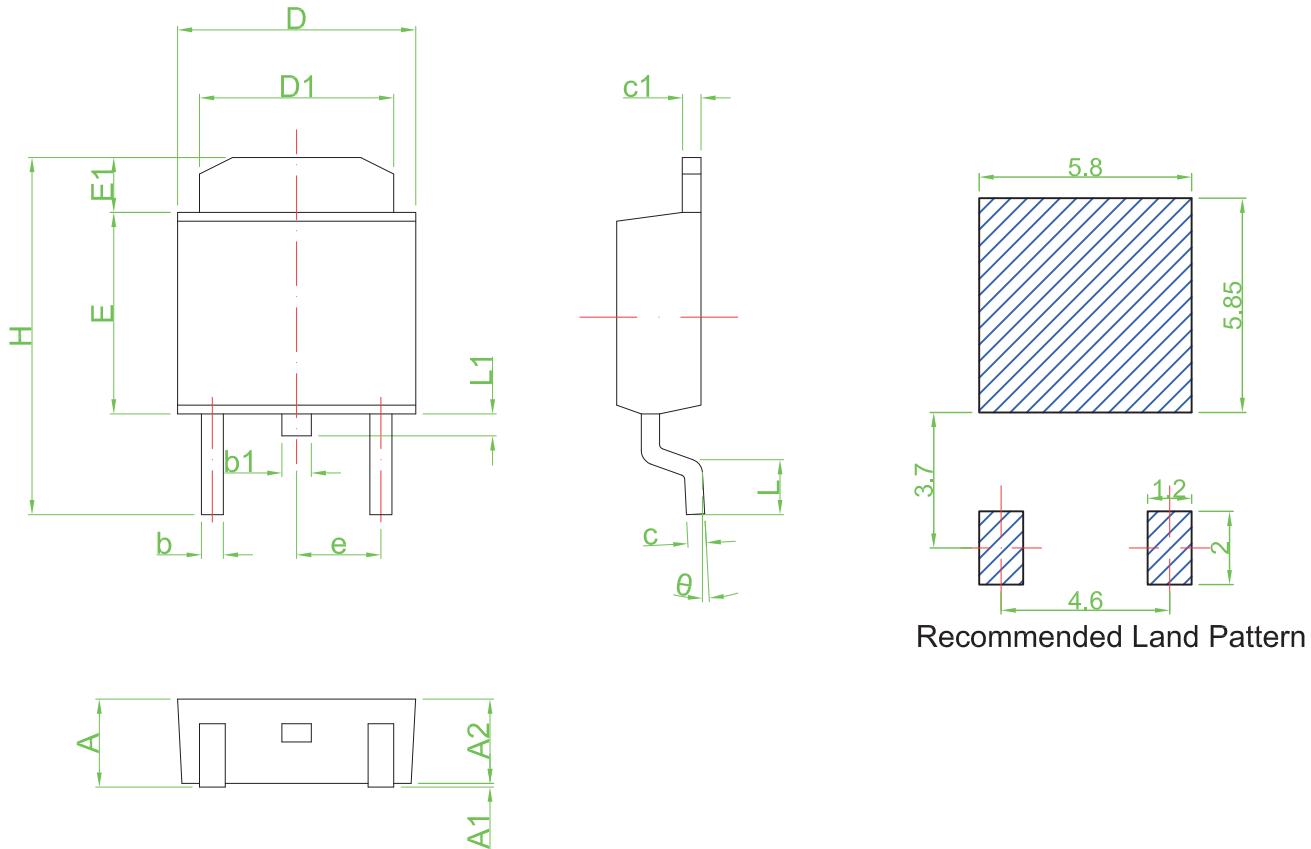
Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM100N34KQ-R	100N34	TO-252	Tape&Reel	2500

PACKAGE	MARKING
TO-252	

TO-252 PACKAGE IN FORMATION



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	2.25	2.65	0.089	0.104
A1	0.00	0.15	0.000	0.006
A2	2.20	2.40	0.087	0.094
b	0.50	0.70	0.020	0.028
b1	0.70	0.90	0.028	0.035
c	0.46	0.66	0.018	0.026
c1	0.46	0.66	0.018	0.026
D	6.30	6.70	0.248	0.264
D1	5.20	5.40	0.205	0.213
E	5.30	5.70	0.209	0.224
E1	1.40	1.60	0.055	0.063
H	9.40	9.90	0.370	0.390
e	2.30 TYP		0.09 TYP	
L	1.40	1.77	0.055	0.070
L1	0.50	0.70	0.020	0.028
θ	0°	8°	0°	8°



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